Claims

1. An adhesive sheet composed of a mixture of two thermoplastics T1 and T2, wherein
   a) the adhesive system has a softening temperature of greater than 65°C and less than 125°C,
   b) a storage modulus G' at 23°C, as measured by test method A, of greater than 10^7 Pas,
   c) a loss modulus G" at 23°C, as measured by test method A, of greater than 10^6 Pas,
   d) and a crossover, as measured by test method A, of less than 125°C.

2. The adhesive sheet of claim 1, characterized in that the layer thickness is between 10 and 100 µm, with particular preference between 30 and 80 µm.

3. The adhesive sheet of at least one of the preceding claims, characterized in that thermoplastics T1 and T2 are selected from the groups consisting of copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolyesters.

4. The adhesive sheet of at least one of the preceding claims, characterized in that reactive resins used additionally comprise epoxy resins, and/or phenolic resins and/or novolak resins.

5. The use of an adhesive sheet of any one of the above claims for bonding chip modules in card bodies.

6. The use of an adhesive sheet of any one of the above claims for bonding polyimide-, polyester or epoxy-based chip modules and on PVC, ABS, PET, PC, PP or PE card bodies.

7. A method for producing a heat-activable adhesive tape, characterized in that an adhesive sheet of claims 1 to 4 is coated onto a release paper or a release film.

6. The method of claim 7, characterized in that the heat-activable adhesive tape is die-cut.

7. The method of at least one of the preceding claims, characterized in that the heat-activable adhesive tape is processed with an implanting die temperature of 150°C.